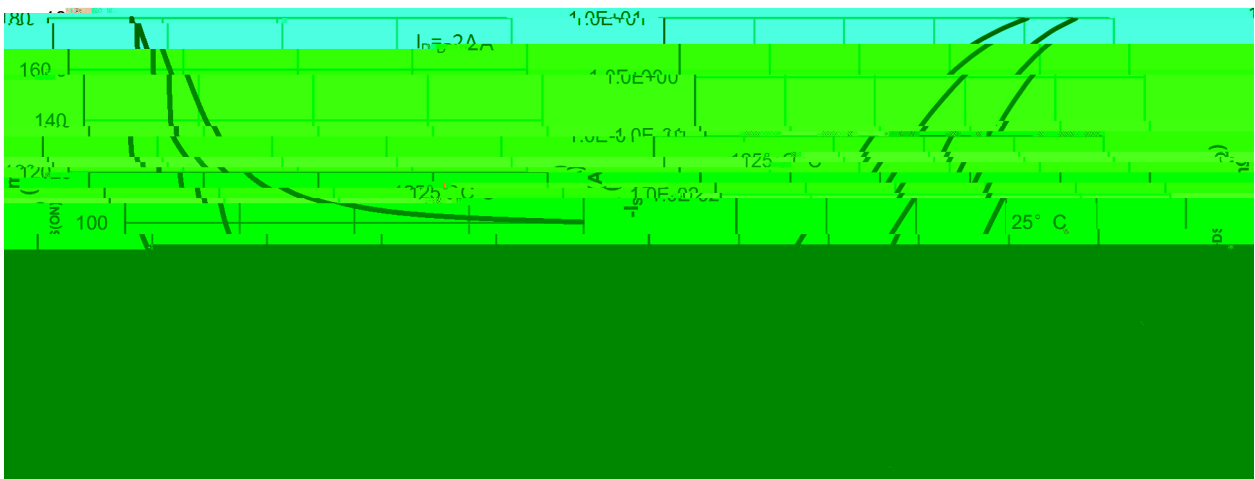
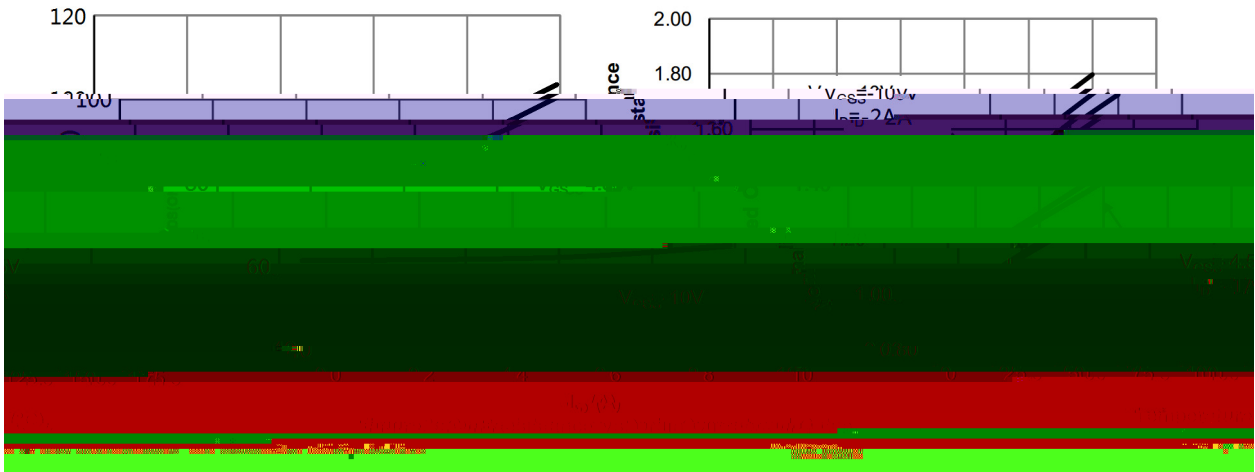
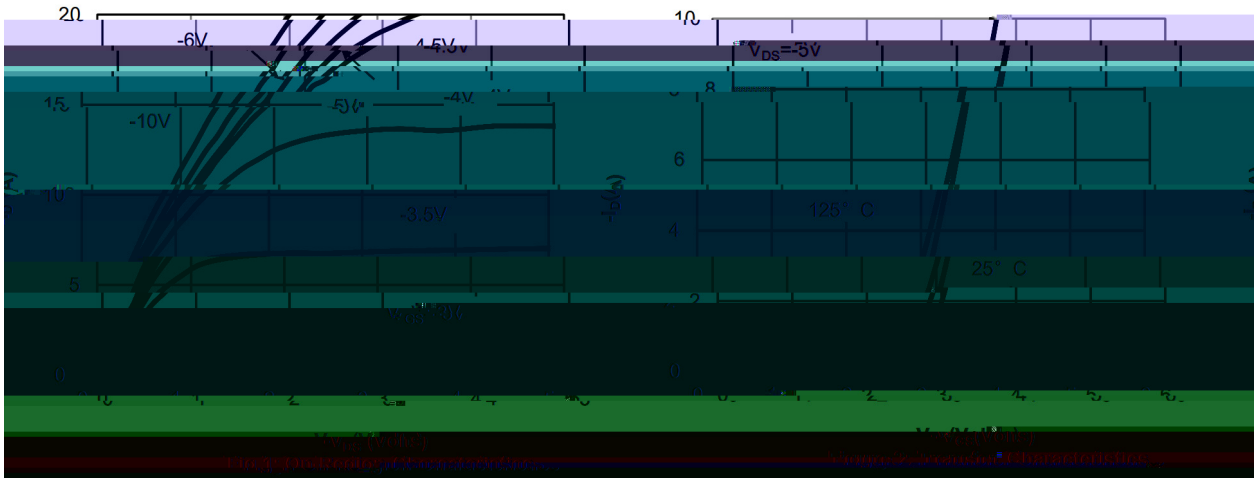
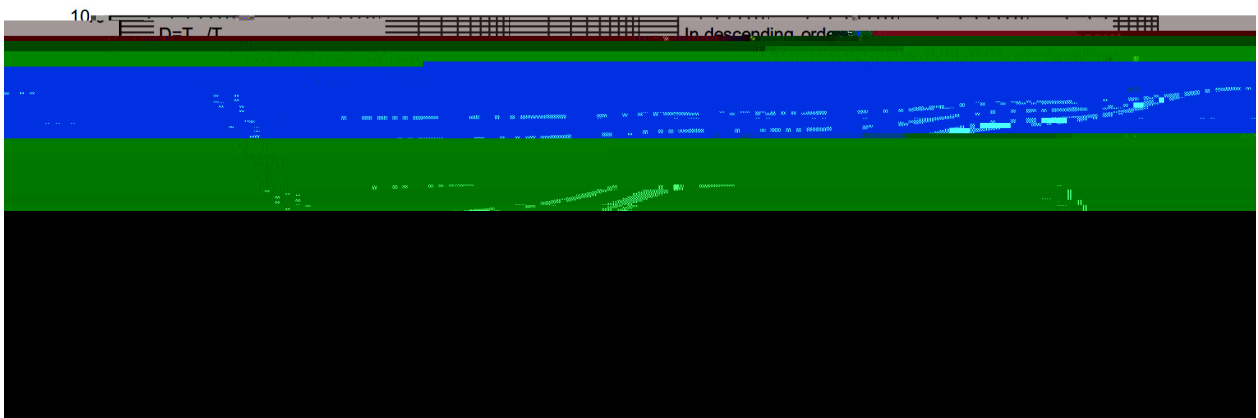
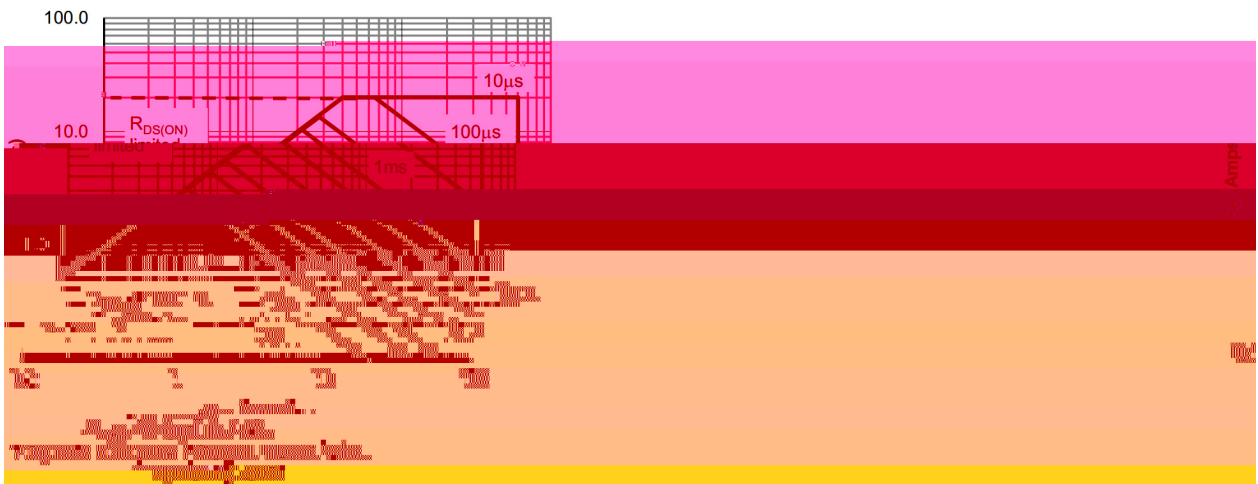
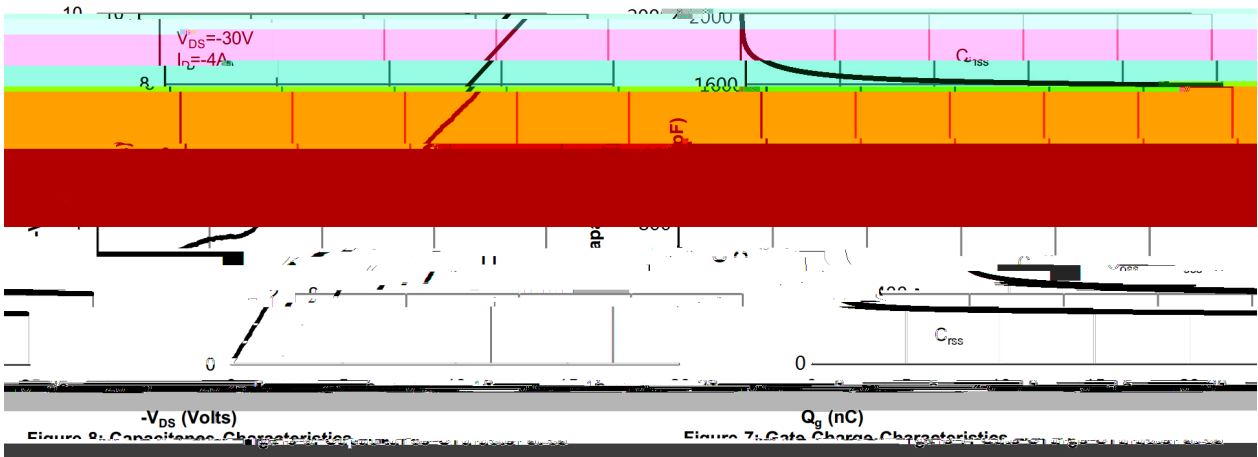
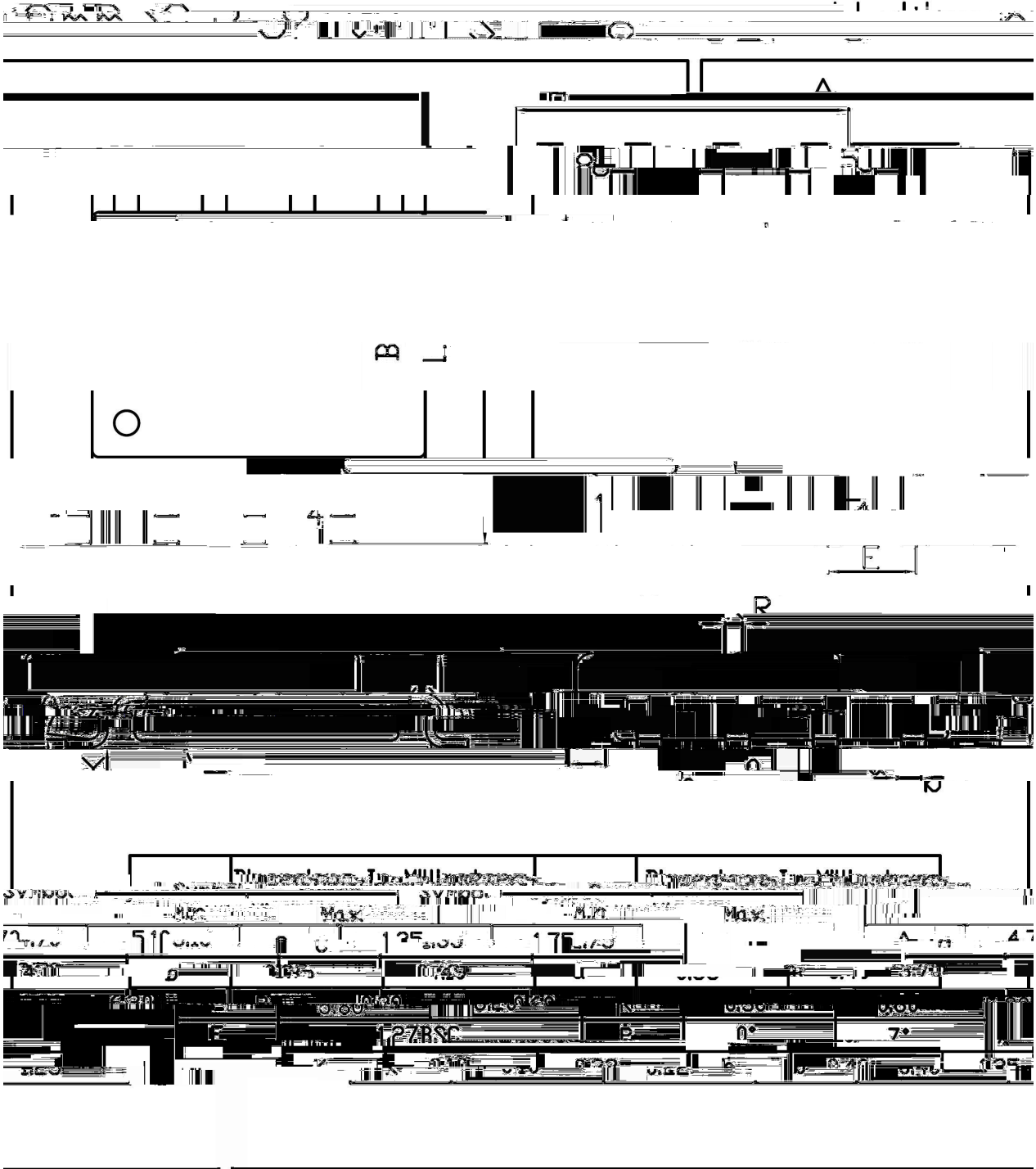


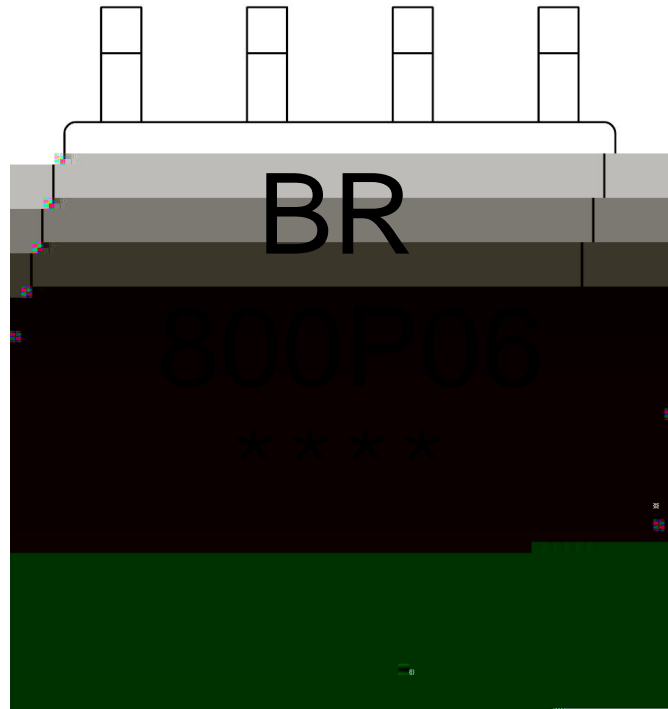
Parameter		Symbol	Rating	Unit
Drain–Source Voltage		V_{DSS}	-60	V
Gate–Body Leakage Voltage		V_{GSS}	± 20	V
Drain Current - Continuous		I_D	-6	A
Power Dissipation (Surface Mounted on FR4 Board, $t = 10$ sec.)		P_D	5.3	W
Operating and Storage Temperature Range		T_J, T_{STG}	-55 150	
Maximum Junction-to-Ambient	$t = 10$ s	R_{JA}	40	/W
Maximum Junction-to-Ambient	Steady-State		75	/W
Maximum Junction-to-Lead	Steady-State	R_{JL}	23.5	/W

Parameter	Symbol	Test Conditions	Min	Typ	Max	Unit
Drain–Source Breakdown Voltage	$V_{(BR)DSS}$	$V_{GS}=0V$ $I_D=-250\mu A$	-60	-71		V
Gate Threshold Voltage	$V_{GS(th)}$	$V_{DS}=V_{GS}$ $I_D=-250\mu A$	-1	-2.1	-3	V
Static Drain–Source On–Resistance	$R_{DS(on)}$	$V_{GS}=-10V$ $I_D=-2A$		61	80	m
		$V_{GS}=-4.5V$ $I_D=-1A$		77	120	m
Zero Gate Voltage Drain Current	I_{DSS}	$V_{DS}=-60V$ $V_{GS}=0V$			-1.0	μA
Gate–Body Leakage.	I_{GSS}	$V_{GS}=-20V$			-100	nA
		$V_{GS}=20V$			100	nA
Drain-Source Diode Forward Voltage	V_{SD}	$V_{GS}=0V$ $I_S=-1A$ $T_J=25$				









BR

800P06

Note:

BR: Company Code

800P06: Product Type

****: Lot No. Code, code change with Lot No

Temperature Profile for IR Reflow Soldering(Pb-Free)

Note:

1 150 180 60